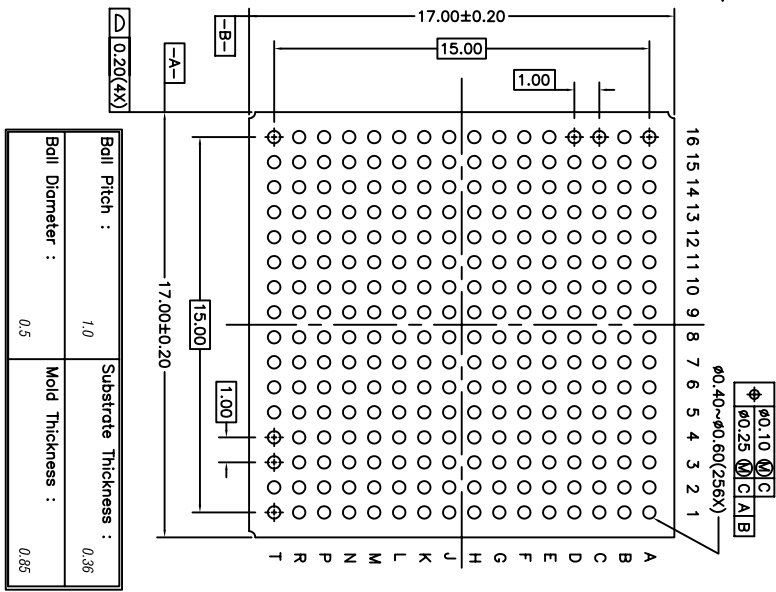
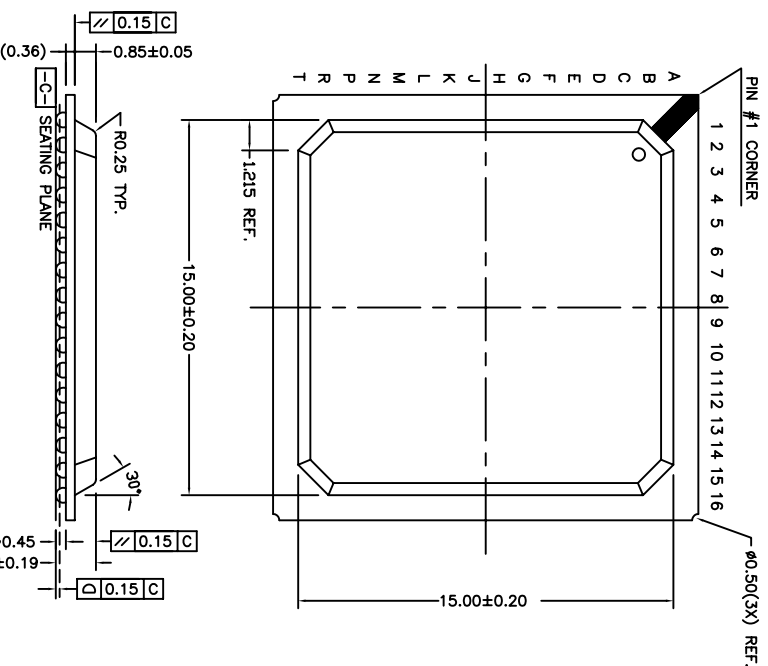


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/05/13	KS



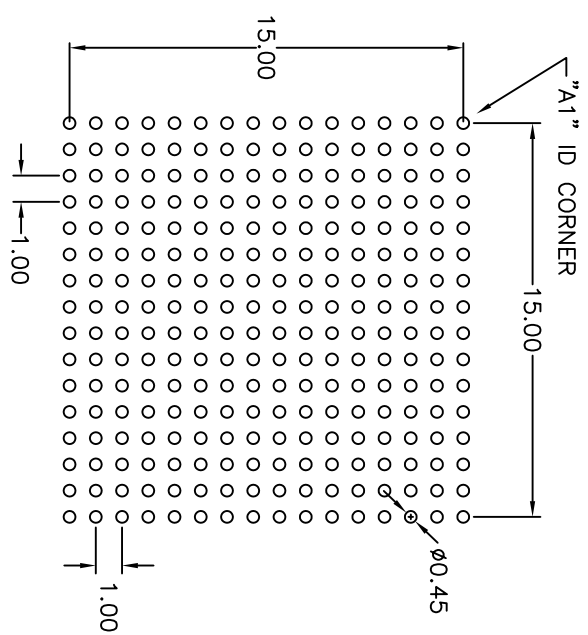
Ball Pitch :	1.0	Substrate Thickness :	0.36
Ball Diameter :	0.5	Mold Thickness :	0.85

TOLERANCES UNLESS SPECIFIED
 DECIMAL ANGULAR ±1°
 XXX±.05
 XXXX±.030

IDT
 www.IDT.com
 6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138
 PHONE: (408) 284-8200 FAX: (408) 284-3572

TITLE AM/AMG 256 PACKAGE OUTLINE
 DRAWN *gdlc* DATE 7/7/09
 CHECKED
 SIZE C DRAWING No. PSC-4263
 DO NOT SCALE DRAWING SHEET 1 OF 2

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/09	P.PAIK
01	COMBINE POD & LAND PATTERN	06/05/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		www.IDT.com		6024 SILVER CREEK VALLEY ROAD, SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572	
DECIMAL	ANGULAR				
XX± .1	±1°				
XXX± .05					
XXXX± .030					
APPROVALS	DATE	TITLE		SIZE	REV
DRAWN: <i>dadg</i>	7/7/09	AM/AMG 256 PACKAGE OUTLINE		C	01
CHECKED		1.00 mm PITCH PBGA		DRAWING No.	
				PSC-4263	
		DO NOT SCALE DRAWING			
					SHEET 2 OF 2